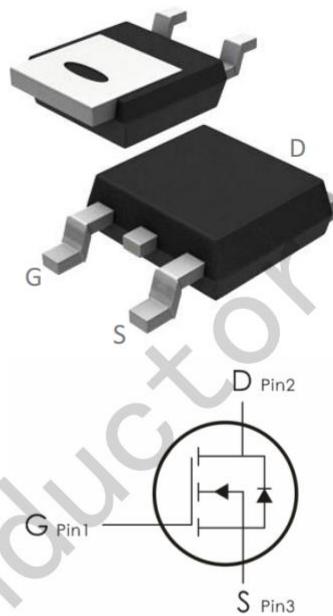


## Description:

This N-Channel MOSFET uses advanced SGT technology and design to provide excellent  $R_{DS(on)}$  with low gate charge. It can be used in a wide variety of applications.



## Features:

- 1)  $V_{DS}=60V, I_D=68 A, R_{DS(ON)}<10m\Omega @V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra  $R_{DS(ON)}$ .
- 5) Excellent package for good heat dissipation.

## Absolute Maximum Ratings: ( $T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current- $T_C=25^\circ C$ <sup>1</sup>	68	A
	Continuous Drain Current- $T_C=100^\circ C$	---	
	Pulsed Drain Current <sup>2</sup>	204	
$E_{AS}$	Single Pulse Avalanche Energy <sup>4</sup>	91	mJ
$P_D$	Power Dissipation, $T_C=25^\circ C$	81	W
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

## Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{eJC}$	Thermal Resistance,Junction to Case	1.54	$^\circ C/W$
$R_{eJA}$	Thermal Resistance,Junction to Ambient <sup>5</sup>	62	

Electrical Characteristics: ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250 \mu\text{A}$	60	---	---	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=60\text{V}$	---	---	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{A}$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250 \mu\text{A}$	1	---	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	---	7.5	10	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=10\text{A}$	---	10	13	
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	1204	---	pF
$C_{\text{oss}}$	Output Capacitance		---	194.1	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	9.9	---	
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}, I_{\text{D}}=25\text{A}, V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=3\Omega$	---	23.9	---	ns
$t_r$	Rise Time		---	4.6	---	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	37.8	---	ns
$t_f$	Fall Time		---	6.4	---	ns
$Q_g$	Total Gate Charge	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=50\text{V}, I_{\text{D}}=25\text{A}$	---	17.9	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	3.8	---	nC
$Q_{\text{gd}}$	Gate-Drain "Miller" Charge		---	4.2	---	nC
<b>Drain-Source Diode Characteristics</b>						
$V_{\text{SD}}$	Source-Drain Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=20\text{A}$	---	---	1.3	V
$I_{\text{S}}$	Continuous Source Current	$V_{\text{GS}} < V_{\text{th}}$	---	68	A	

<b>trr</b>	Reverse Recovery Time	$I_S=25\text{ A}$ , $di/dt=100\text{ A}/\mu\text{s}$	36.3	---	Ns
<b>qrr</b>	Reverse Recovery Charge		1.4	---	nc

**Notes:**

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 4)  $V_{DD}=30\text{ V}$ ,  $R_G=50\text{ }\Omega$ ,  $L=0.3\text{ mH}$ , starting  $T_j=25\text{ }^\circ\text{C}$ .
- 5) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25\text{ }^\circ\text{C}$ .

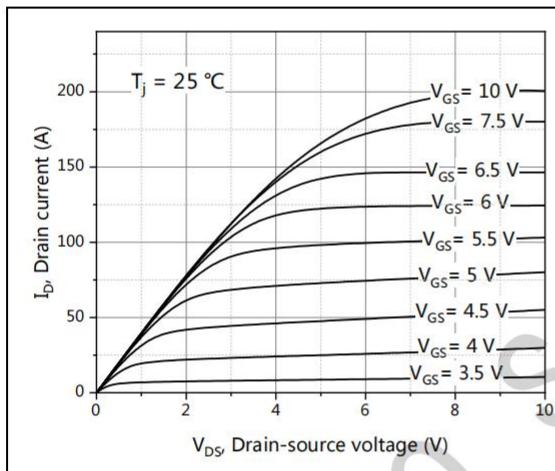
**Typical Characteristics:** ( $T_c=25\text{ }^\circ\text{C}$  unless otherwise noted)


Figure 1, Typ. output characteristics

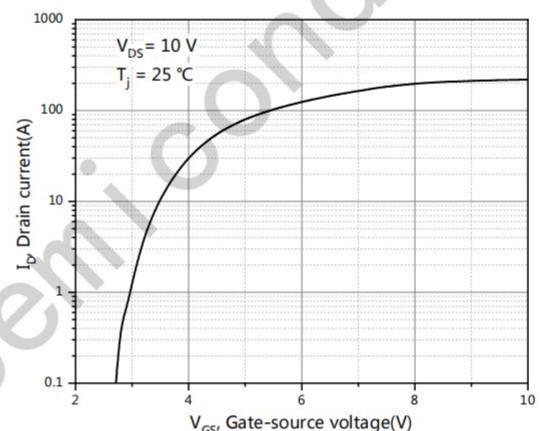


Figure 2, Typ. transfer characteristics

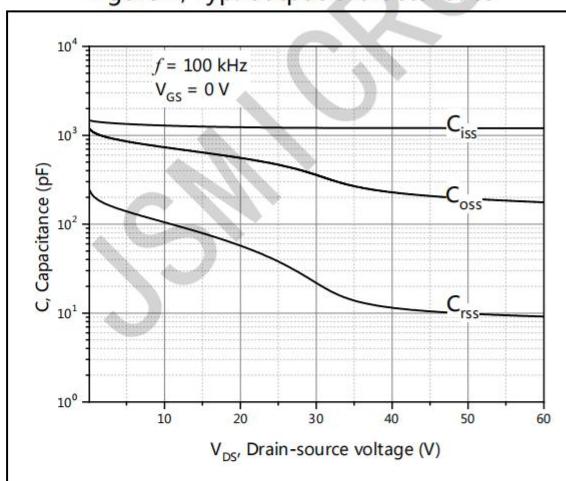


Figure 3, Typ. capacitances

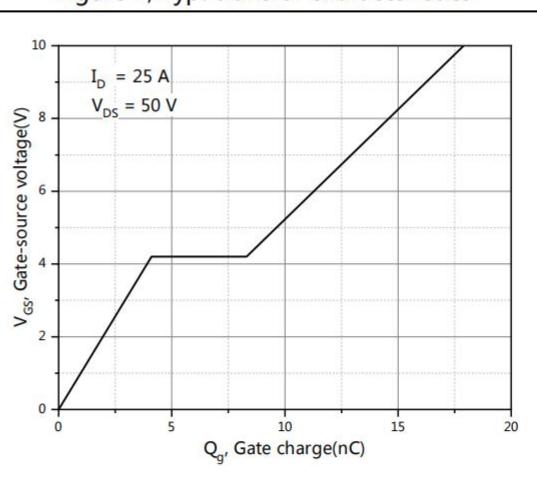
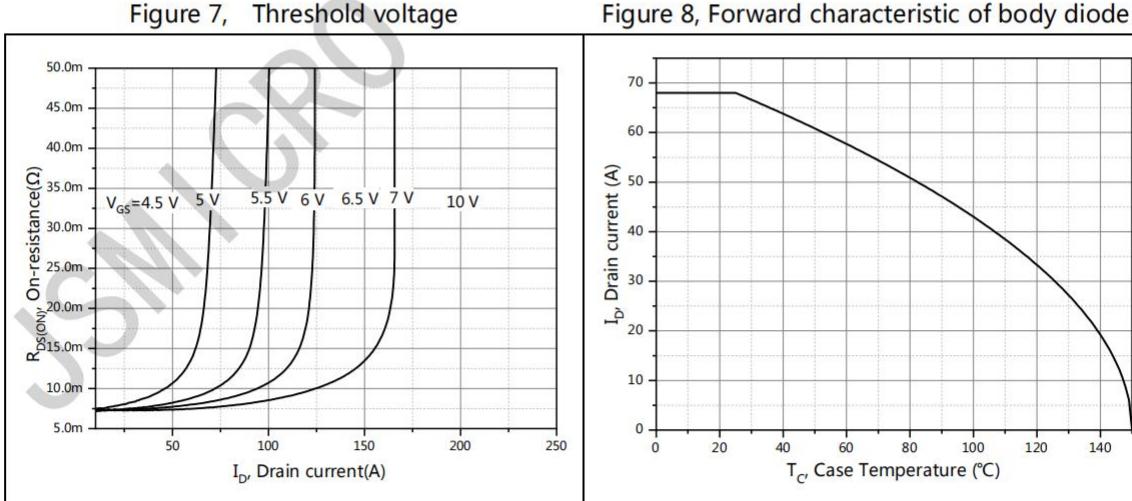
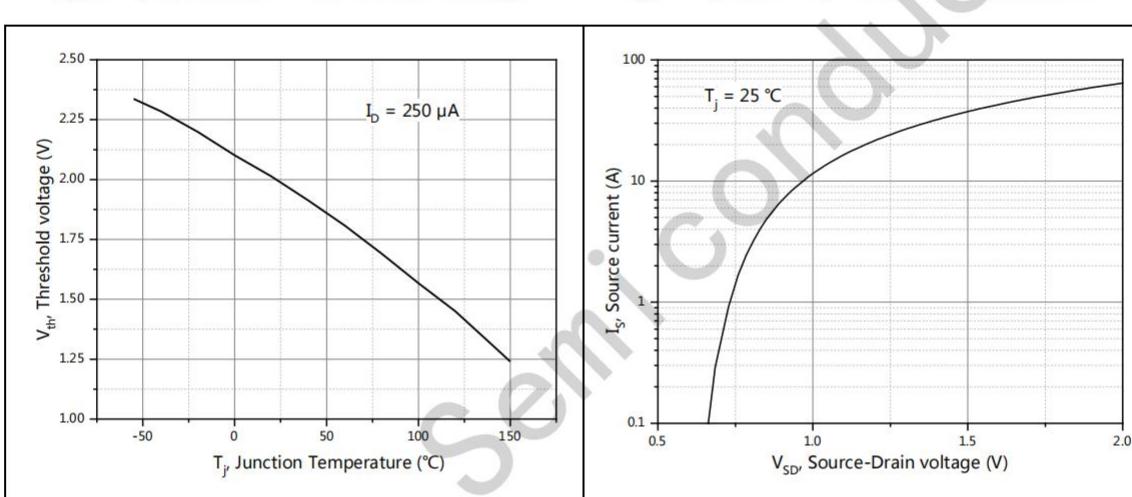
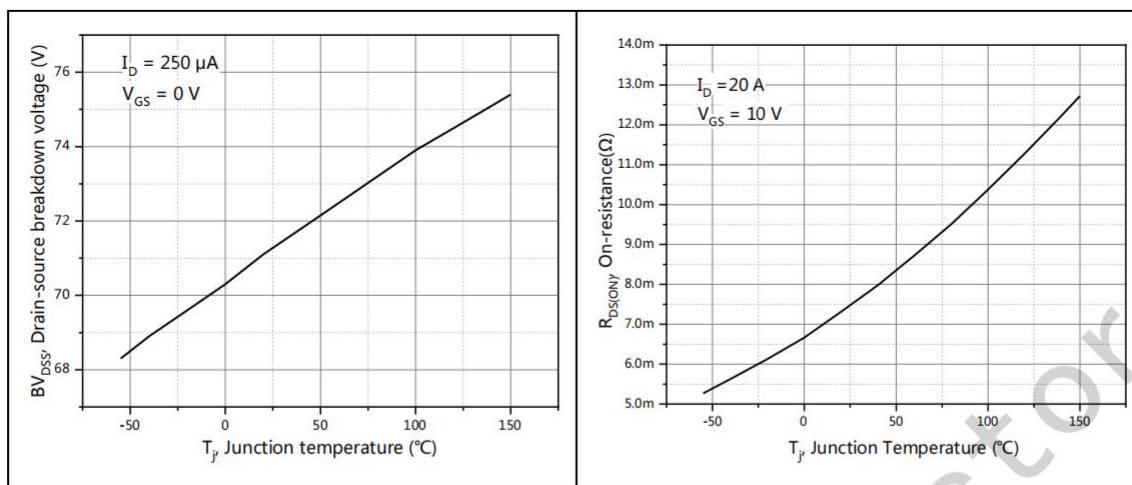


Figure 4, Typ. gate charge



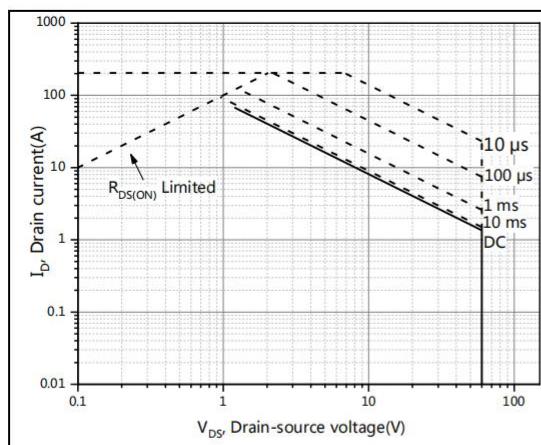
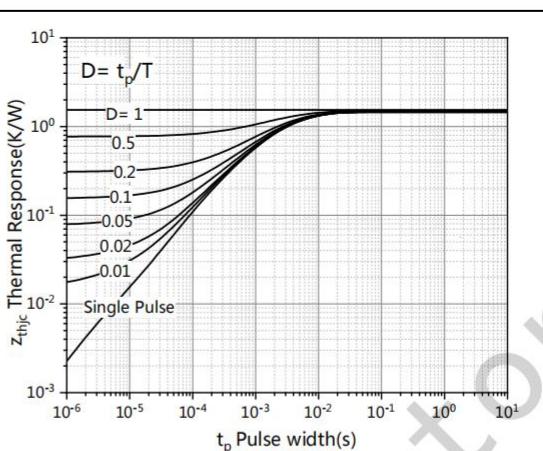
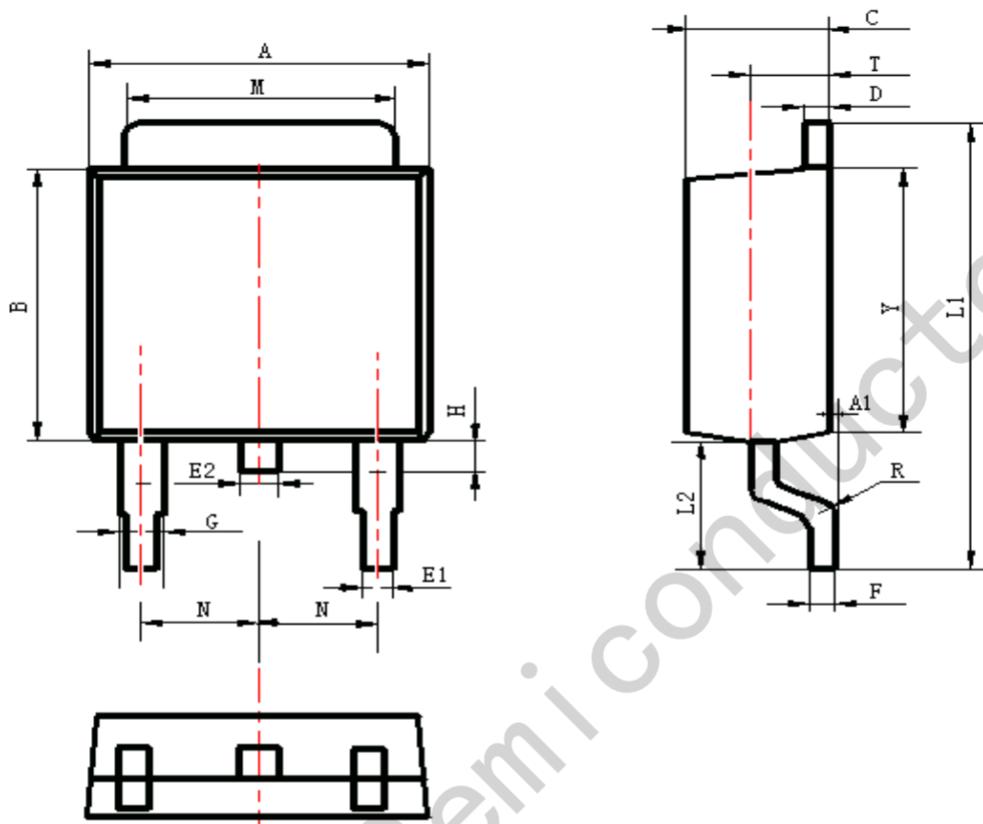

 Figure 11, Safe operation area  $T_C=25\text{ }^{\circ}\text{C}$ 


Figure 12, Max. transient thermal impedance

## Package Information

TO-252



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	6.30	6.90	0.248	0.272
A1	0.00	0.16	0.000	0.006
B	5.70	6.30	0.224	0.248
C	2.10	2.50	0.083	0.098
D	0.30	0.70	0.012	0.028
E1	0.60	0.90	0.024	0.035
E2	0.70	1.00	0.028	0.039
F	0.30	0.60	0.012	0.024
G	0.70	1.20	0.028	0.047
L1	9.60	10.50	0.378	0.413
L2	2.70	3.10	0.106	0.122
H	0.40	1.00	0.016	0.039
M	5.10	5.50	0.201	0.217
N	2.09	2.49	0.082	0.098
R	0.30		0.012	
T	1.40	1.60	0.055	0.063
Y	5.10	6.30	0.201	0.248